TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

TPCS8211

Lithium Ion Battery Applications
Notebook PC Applications
Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: $RDS(ON) = 16 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current: $IDSS = 10 \mu A (max) (VDS = 20 V)$
- Enhancement mode: $V_{th} = 0.5 \sim 1.2 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 200 \text{ }\mu\text{A})$

Absolute Maximum Ratings (Ta = 25°C)

Char	acteristics	Symbol	Rating	Unit	
Drain-source vol	tage	V_{DSS}	20	V	
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V_{DGR}	20	V	
Gate-source volt	age	V _{GSS}	±12	V	
Drain current	DC (Note 1)	I _D	6	А	
Drain current	Pulse (Note 1)	VDSS 20 VDGR 20 VGSS ±12 1) ID 6 1) IDP 24 Ba) PD (1) 1.1 e PD (2) 0.75 Ba) PD (1) 0.6 e PD (2) 0.35 4) EAS 46.8 IAR 6 n EAR 0.075	A		
Drain power	Single-device operation (Note 3a)	P _{D (1)}	1.1		
dissipation (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.75	W	
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.6	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.35		
Single pulse avalanche energy (Note 4)		E _{AS}	46.8	mJ	
Avalanche curre	nt	I _{AR}	6	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.075	mJ	
Channel tempera	ature	T _{ch}	150	°C	
Storage tempera	ture range	T _{stg}	-55~150	°C	

Unit: mm

(0.525)

1. DRAIN 0 5. GATE
2. 3. SOURCE 6. 7. SOURCE
4. GATE 8. DRAIN

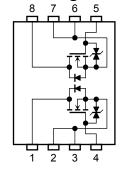
JEDEC —

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Weight: 0.035 g (typ.)

Circuit Configuration



Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

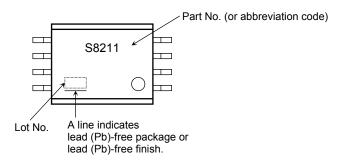
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Please handle with caution.

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
Thermal registance, abancel to embient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	114	°C/W	
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	167		
Thermal resistance, shannel to embient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	208		
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	357	°C/W	

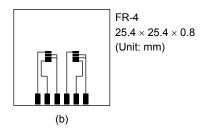
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

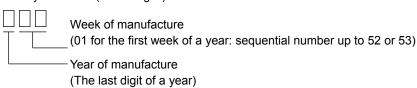
Note 2:

- a) Device mounted on a glass-epoxy board (a)
 - FR-4 25.4 × 25.4 × 0.8 (Unit: mm)
- b) Device mounted on a glass-epoxy board (b)



Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).
- Note 4: $V_{DD}=16~V,~T_{ch}=25^{\circ}C$ (initial), $L=1.0~mH,~R_{G}=25~\Omega,~I_{AR}=6~A$
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature.
- Note 6: on lower right of the marking indicates Pin 1.
 - Weekly code: (Three digits)



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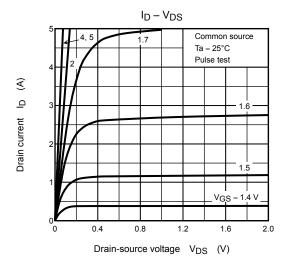
Electrical Characteristics (Ta = 25°C)

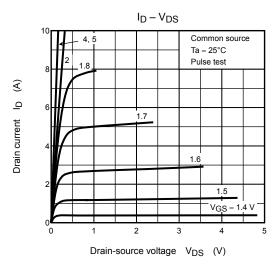
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-OFF cu	ırrent	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	10		10	μА
Drain-source bre	akdown voltago	V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	20	_	_	V
Diam-source bre	akuowii voitage	V _{(BR) DSX}	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8			V
Gate threshold v	oltage	V _{th}	$V_{DS} = 10 \text{ V}, I_D = 200 \mu\text{A}$	0.5		1.2	V
			$V_{GS} = 2.0 \text{ V}, I_D = 4.2 \text{ A}$		26	45	
Drain-source ON resistance		R _{DS} (ON)	$V_{GS} = 2.5 \text{ V}, I_D = 4.2 \text{ A}$	_	21	29	mΩ
			$V_{GS} = 4.0 \text{ V}, I_D = 4.8 \text{ A}$	_	16	24	
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 3.0 \text{ A}$	5.5	11	_	S
Input capacitance	Input capacitance			_	1590	_	
Reverse transfer	capacitance	C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	180	_	pF
Output capacitance		Coss		_	200	_	
Switching time	Rise time	t _r	VGS 5 V	_	6.4	_	
	Turn-ON time	t _{on}			22		ns
	Fall time	t _f			10		. 115
	Turn-OFF time	t _{off}	V _{DD} ≃ 10 V Duty ≦ 1%, t _W = 10 μs		42		
Total gate charge (gate-source plus gate-drain)		Qg		_	20	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 16 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6 \text{ A}$		3.5		nC
Gate-drain ("miller") charge		Q _{gd}		_	4.5		

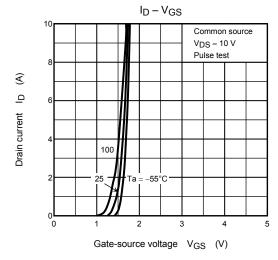
Source-Drain Ratings and Characteristics (Ta = 25°C)

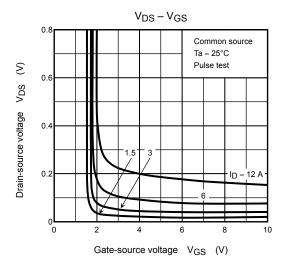
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	24	Α
Forward voltage (diode)		V _{DSF}	I _{DR} = 6 A, V _{GS} = 0 V	_	_	-1.2	V

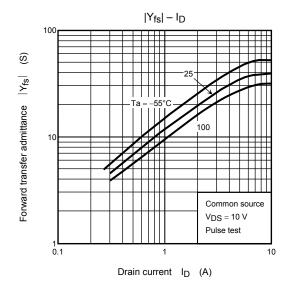
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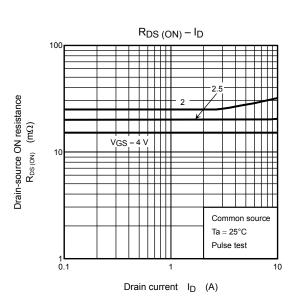


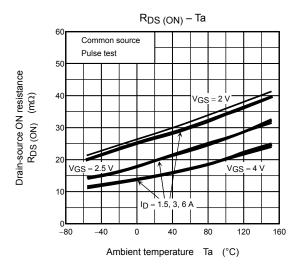


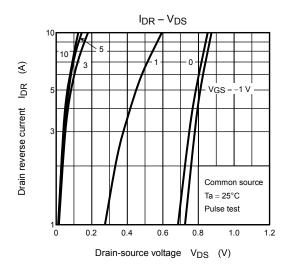


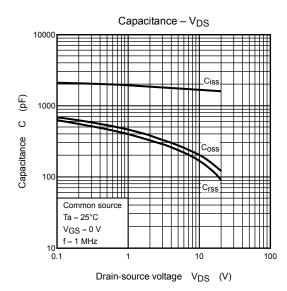


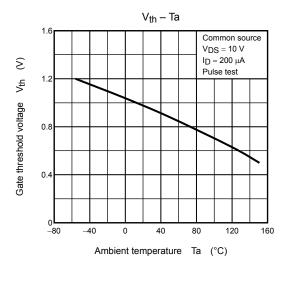


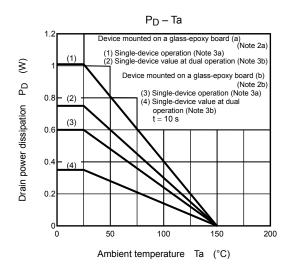


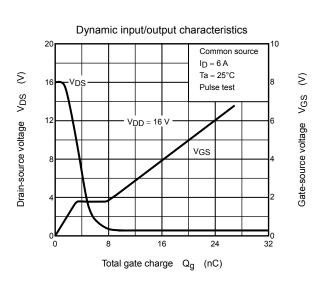


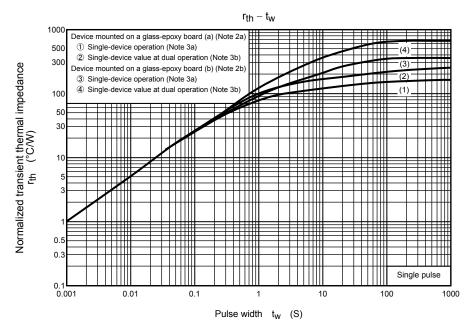




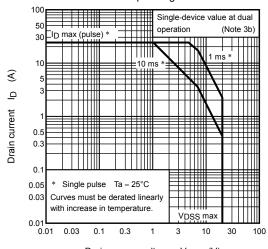












Drain-source voltage V_{DS} (V)

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